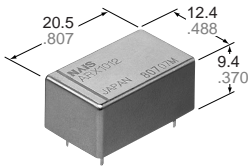


NAIS

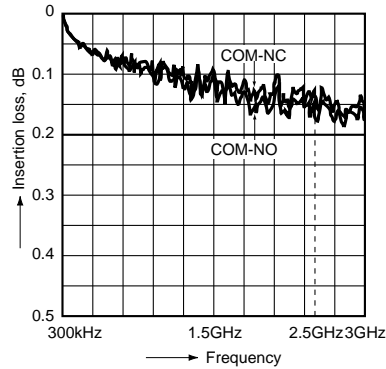
SMALL MICRO WAVE RELAY

RX-RELAYS



mm inch

• Insertion loss



• V.S.W.R./ Return loss: 1.2dB or less/
20.8dB or more

2. High sensitivity

• Nominal operating power: 200 mW

3. Small size

• Size: 20.5(L) × 12.4(W) × 9.4(H) mm
.807(L) × .488(W) × .370(H) inch

*Also available for unit support (contact us for more details).

1. Excellent high frequency characteristics (~2.5GHz, Impedance 50Ω)

- Insertion loss: 0.2 dB or less
- Isolation: 60 dB or more

SPECIFICATIONS

Contact

Arrangement	1 Form C		
Contact material	Gold		
Initial contact resistance	Max. 100 mΩ		
Rating	Contact rating	10W (2.5 GHz, Impedance 50 Ω, V.S.W.R. ≤1.2) 10mA 24V DC(resistive load)	
	Contact carrying power	Max. 20W(at 40°C, V.S.W.R. ≤1.2, Average)	
	Max. switching voltage	30 V DC	
	Max. switching current	0.5 A DC	
High frequency characteristics (~2.5GHz, Impedance 50Ω)	Isolation	Min. 60 dB	
	Insertion loss	Max. 0.2 dB	
	V.S.W.R.(Return loss)	Max. 1.2 (Min. 20.8dB)	
Expected life (min. operations)	Electrical	10mA 24 V DC (resistive load)	3×10 ⁵
		10W 2.5 GHz, Impedance 50Ω	10 ⁵

Coil (at 20°C, 68°F)

	Nominal operating power
Single side stable	200 mW
1 coil latching	200 mW
2 coil latching	400 mW

Characteristics

Initial insulation resistance* ¹		Min. 100 MΩ (at 500 V DC)
Initial breakdown voltage* ²	Between open contacts	500 Vrms
	Between contact and coil	1,000 Vrms
	Between contact and earth terminal	500 Vrms
Operate time [Set time]* ³ (at 20°C)		Max. 10ms (Approx. 6ms) [Max. 10ms (Approx. 5ms)]
Release time (without diode) [Reset time]* ³		Max. 6ms (Approx. 3ms) [Max. 10ms (Approx. 5ms)]
Temperature rise (at 20°C)* ⁴		Max. 60°C
Shock resistance	Functional* ⁵	Min. 200 m/s ² {20 G}
	Destructive* ⁶	Min. 1,000 m/s ² {100 G}
Vibration resistance	Functional* ⁷	10 to 55 Hz at double amplitude of 3 mm
	Destructive	10 to 55 Hz at double amplitude of 5 mm
Conditions for operation, transport and storage* ⁸ (Not freezing and condensing at low temperature)	Ambient temp.	-40°C to 60°C -40°F to 140°F
	Humidity	5 to 85% R.H.
Unit weight		Approx. 5 g .18 oz

Remarks

- * Specifications will vary with foreign standards certification ratings.
- *¹ Measurement at same location as "Initial breakdown voltage" section.
- *² Detection current: 10mA
- *³ Nominal operating voltage applied to the coil, excluding contact bounce time.
- *⁴ By resistive method, nominal voltage applied to the coil: Contact carrying power: 20W, at 2.5GHz, Impedance 50Ω, V.S.W.R. ≤ 1.2
- *⁵ Half-wave pulse of sine wave: 11ms, detection time: 10μs.
- *⁶ Half-wave pulse of sine wave: 6ms
- *⁷ Detection time: 10μs
- *⁸ Refer to 5. Conditions for operation, transport and storage mentioned in AMBIENT ENVIRONMENT (Page 61)

TYPICAL APPLICATIONS

- Cellular phone base station (W-CDMA, FPLMTS, IMT-2000, PCS, DCS)
- Cellular phone-related measurement devices (SP3T/SP4T switches, etc)
- Wireless LAN
- Wireless Local Loop

ORDERING INFORMATION

Ex.	A	RX	1	0	12
Product name	Contact arrangement		Operating function		Coil voltage, V DC
RX	1: 1 Form C		0: Single side stable 1: 1 coil latching 2: 2 coil latching		03: 3 09: 9 4H: 4.5 12: 12 06: 6 24: 24

Note: Standard packing; Carton: 50 pcs. Case 500 pcs.

TYPES ANE COIL DATA (at 20°C 68°F)

• Single side stable type

Part No.	Nominal voltage, V DC	Pick-up voltage, V DC (max.)(initial)	Drop-out voltage, V DC (min.)(initial)	Coil resistance, Ω (±10%)	Nominal operating current, mA (±10%)	Nominal operating power, mW	Max. allowable voltage, V DC
ARX1003	3	2.25	0.3	45	66.7	200	3.3
ARX104H	4.5	3.375	0.45	101	44.4	200	4.95
ARX1006	6	4.5	0.6	180	33.3	200	6.6
ARX1009	9	6.75	0.9	405	22.2	200	9.9
ARX1012	12	9	1.2	720	16.7	200	13.2
ARX1024	24	18	2.4	2,880	8.3	200	26.4

• 1 coil latching type

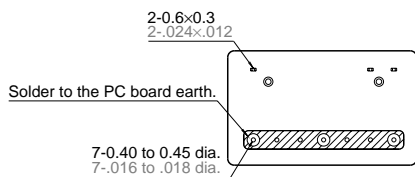
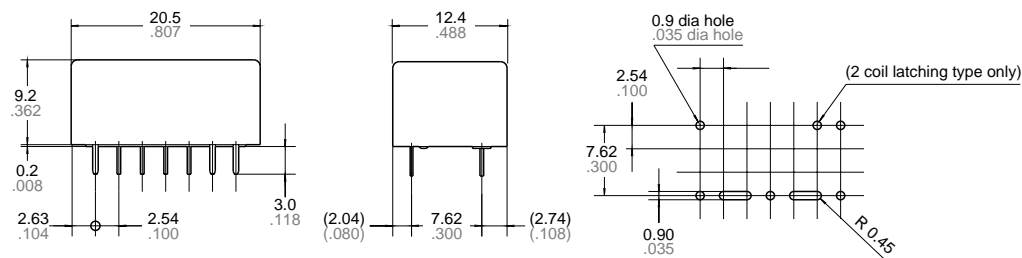
Part No.	Nominal voltage, V DC	Set voltage, V DC (max.)(initial)	Reset voltage, V DC (max.)(initial)	Coil resistance, Ω (±10%)	Nominal operating current, mA (±10%)	Nominal operating power, mW	Max. allowable voltage, V DC
ARX1103	3	2.25	2.25	45	66.7	200	3.3
ARX114H	4.5	3.375	3.375	101	44.4	200	4.95
ARX1106	6	4.5	4.5	180	33.3	200	6.6
ARX1109	9	6.75	6.75	405	22.2	200	9.9
ARX1112	12	9	9	720	16.7	200	13.2
ARX1124	24	18	18	2,880	8.3	200	26.4

• 2 coil latching type

Part No.	Nominal voltage, V DC	Set voltage, V DC (max.)(initial)	Reset voltage, V DC (max.)(initial)	Coil resistance, Ω (±10%)	Nominal operating current, mA (±10%)	Nominal operating power, mW	Max. allowable voltage, V DC
ARX1203	3	2.25	2.25	22.5	133.3	400	3.3
ARX124H	4.5	3.375	3.375	50.6	88.9	400	4.95
ARX1206	6	4.5	4.5	90	66.7	400	6.6
ARX1209	9	6.75	6.75	202.5	44.4	400	9.9
ARX1212	12	9	9	360	33.3	400	13.2
ARX1224	24	18	18	1,440	16.7	400	26.4

DIMENSIONS

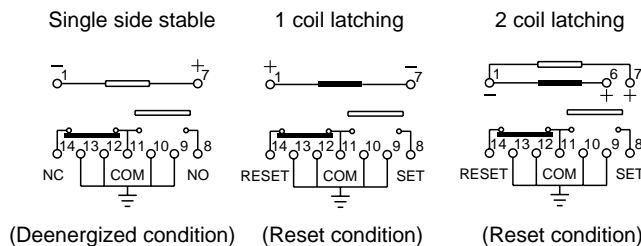
mm inch



General tolerance: ±0.3 ±0.12

Tolerance: ±0.1 ±0.04

Schematic (Bottom view)



REFERENCE DATA

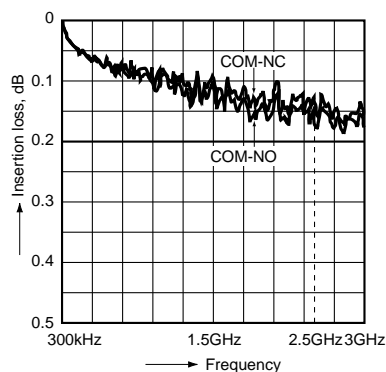
1. High frequency characteristics

Sample: ARX1012

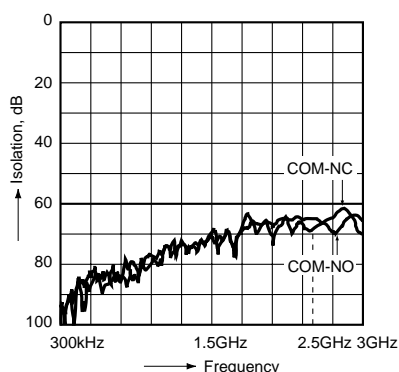
Measuring method: Measured with HP network analyzer (HP8753C).

The details for the high frequency characteristics and the measurement procedures and conditions are listed in the RX relay test report.

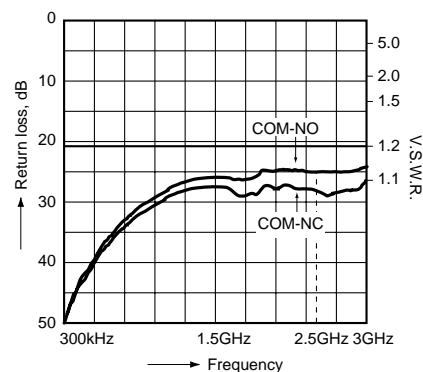
• Insertion loss



• Isolation



• V.S.W.R. (Return loss)



NOTES

1. Coil operating power

Pure DC current should be applied to the coil. The wave form should be rectangular. If it includes ripple, the ripple factor should be less than 5%.

However, check it with the actual circuit since the characteristics may be slightly different. The nominal operating voltage should be applied to the coil for more than 30 ms to set/reset the latching type relay.

2. Coil connection

When connecting coils, refer to the wiring diagram to prevent mis-operation or malfunction.

3. External magnetic field

Since RX relays are highly sensitive polarized relays, their characteristics will be affected by a strong external magnetic field. Avoid using the relay under that condition.

4. Cleaning

For automatic cleaning, the boiling method is recommended. Avoid ultrasonic cleaning which subjects the relays to high frequency vibrations, which may cause the contacts to stick.

It is recommended that a fluorinated hydrocarbon or other alcoholic solvents be used.

5. Soldering

The soldering shall be performed under following condition.

Max. 260°C 500°F 10s

Max. 350°C 662°F 3s

In addition, when soldering the case to the PC board, the plating may swell depending on the soldering conditions.

For Cautions for Use, see Relay Technical Information